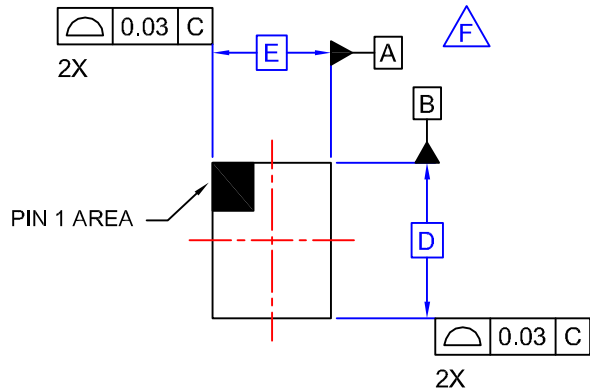
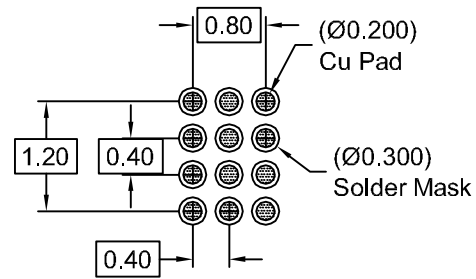


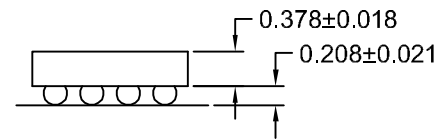
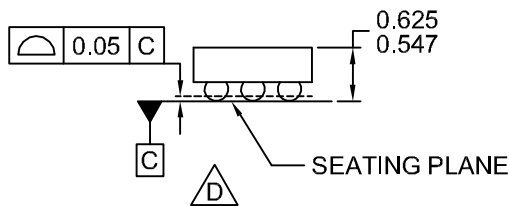
REVISIONS			
REV	DESCRIPTION	DATE	APP'D / SITE
1	Initial drawing release.	8-19-09	L. England / FSME



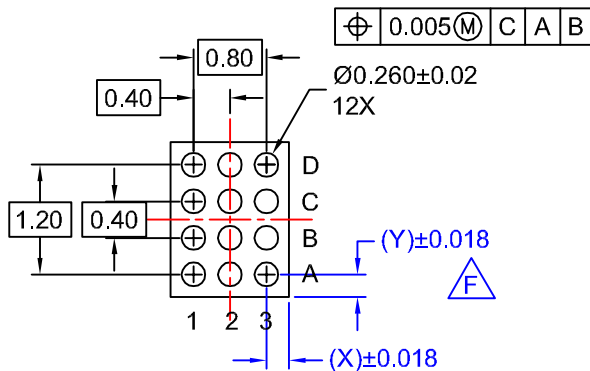
TOP VIEW



RECOMMENDED LAND PATTERN
(NSMD PAD TYPE)



SIDE VIEWS



BOTTOM VIEW

NOTES:

A. NO JEDEC REGISTRATION APPLIES.

B. DIMENSIONS ARE IN MILLIMETERS.

C. DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 1994.

D. DATUM C IS DEFINED BY THE SPHERICAL CROWNS OF THE BALLS.

E. PACKAGE NOMINAL HEIGHT IS 586 MICRONS ±39 MICRONS (547-625 MICRONS).

F. FOR DIMENSIONS D, E, X, AND Y SEE PRODUCT DATASHEET.

G. DRAWING FILENAME: MKT-UC012ACrev1.

APPROVALS		DATE	FAIRCHILD SEMICONDUCTOR™ 12BALL WLCSP, 3X4 ARRAY 0.4MM PITCH, 250UM BALL			
DRAWN	L. England	8-19-09				
DFTG. CHK.	S. Martin	8-19-09				
ENGR. CHK.						
PROJECTION INCH [MM]			SCALE	SIZE	DRAWING NUMBER	REV
			N/A	N/A	MKT-UC012AC	1
			DO NOT SCALE DRAWING		SHEET 1 of 1	